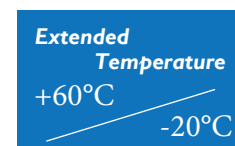


1U fanless 19" DC-DC Redundant Server

Intel® i7-9700TE Processor, Rich I/O interface, DC-DC Power Supply with Redundant support, Operating temp. -20 ~ 60°C



- Intel® Coffee Lake-Refresh i7-9700TE (8 Cores, 3.8GHz)
- 2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
- 1 x PCIe x16 Slot
- 1 x M.2(Key M, PCIe x4 and SATA3) Expansion Slot
- 6 x USB, 3 x DisplayPort, 2 x LAN, 1 x Line-out/Mic
- 2 x 2.5" SATA HDD/ SSD Easy Swap Tray
- 2 x 150W DC-DC Power Supply with Redundant support
- Wide range 9~36V DC-in
- Extended Operating Temperature -20 to 60°C



Specifications ▶

Specifications	
High Performance Processor	Intel® 9th Gen. Core™ i7-9700TE (Frequency 1.8 GHz, Turbo Boost up to 3.8 GHz), 8 Cores, 8 Threads Support, 12 MB SmartCache. Build-in UHD Graphics 630 for excellent 3D, Optane™ Memory, Turbo Boost Technology 2.0, and VPro support.
Memory	2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
Chipset	Intel® Q370 Chipset
Expansion Slot	1 x PCIe x16 (Graphics card dimension should not be large than 170x110mm) 1 x M.2 (Key M, 2242/2260/2280) with PCIe x4 and SATA3
Display	
DisplayPort	Resolution up to 4096 x 2304 60@Hz
Storage	
HDD/SDD	2 x 2.5" SATA HDD/SSD easy swap tray
Ethernet	
Ethernet	Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps)
Rear I/O	
DisplayPort	3 x DP
Ethernet	2 x RJ45
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
COM	1 x RS232/422/485
USB	4 x USB 3.1(10Gb/s)
DC-IN	1 x 4P Terminal Block
Front I/O	
Button	1 x Power Button w/Indicator LED
Indicator LED	HDD
USB	2 x USB 2.0
Easy Swap SSD Tray	2
Power Requirement	
Power Input	9~36V DC-in

Applications, Operating System	
Applications	Commercial and Industrial Platforms, Embedded Computing, Process Control, Intelligent Automation and manufacturing applications
Operating System	Windows 10 64Bit Ubuntu13.04, Ubuntu13.10, Ubuntu14.04, Fedora 20
Physical	
Dimension (W x D x H)	450 x430 x 44 mm
Weight	8.92Kg
Chassis	SECC
Heatsink	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide
Environmental	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
EMC	CE and FCC compliance
Green Product	RoHS compliance
Operating Temp.	w/o Graphic Card (ET: -20 to 60°C; UT: -30 to 70°C) ; w/Graphic Card (0 to 50°C)
Storage Temp.	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing

Ordering information

ROC285AA-ET

19" 1U Rack-mount Rugged Fanless System with Intel® Coffelake Core i7-9700TE, 3 x DisplayPort, 1 x PCIe x16, 6 x USB, 9~36V DC-in, Operating Temp. -20~+60°C

ROC285AA-UT

19" 1U Rack-mount Rugged Fanless System with Intel® Coffelake Core i7-9700TE, 3 x DisplayPort, 1 x PCIe x16, 6 x USB, 9~36V DC-in, Operating Temp. -30~+70°C

